

# 74LVC2G17-Q100

Dual non-inverting Schmitt trigger with 5 V tolerant input

Rev. 2 — 2 May 2013

Product data sheet

## 1. General description

The 74LVC2G17-Q100 provides two non-inverting buffers with Schmitt trigger input. It is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 V and 5 V environment.

This device is fully specified for partial power-down applications using  $I_{OFF}$ . The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Wide supply voltage range from 1.65 V to 5.5 V
- 5 V tolerant input/output for interfacing with 5 V logic
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD-8B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- $\pm 24\text{ mA}$  output drive ( $V_{CC} = 3.0\text{ V}$ )
- CMOS low-power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Multiple package options

## 3. Applications

- Wave and pulse shapers for highly noisy environments



4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC2G17GW-Q100	−40 °C to +125 °C	SC-88	plastic surface-mounted package; 6 leads	SOT363
74LVC2G17GV-Q100	−40 °C to +125 °C	TSOP6	plastic surface-mounted package (TSOP6); 6 leads	SOT457

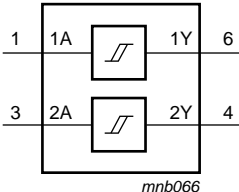
5. Marking

Table 2. Marking codes

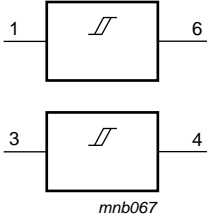
Type number	Marking code <sup>[1]</sup>
74LVC2G17GW-Q100	VV
74LVC2G17GV-Q100	VV

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

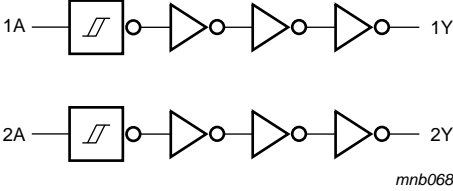
6. Functional diagram



**Fig 1. Logic symbol**



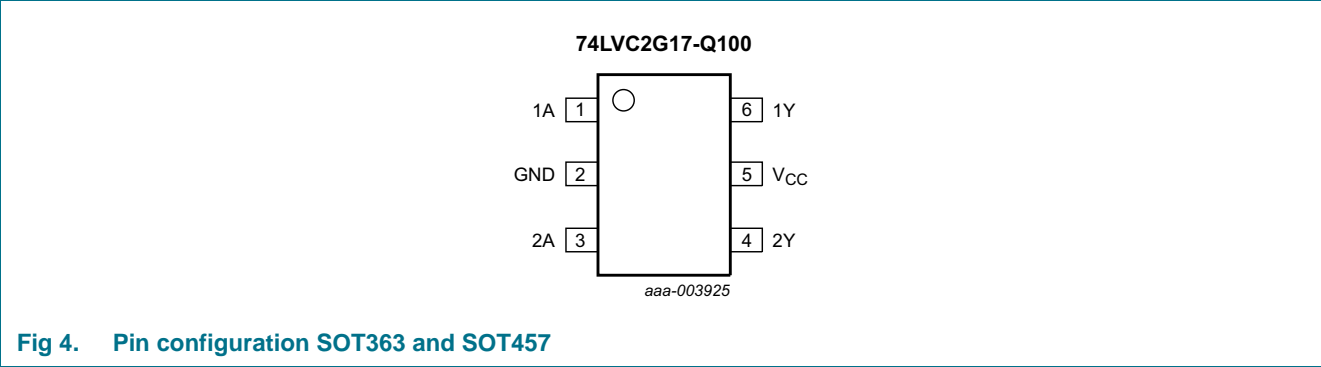
**Fig 2. IEC logic symbol**



**Fig 3. Logic diagram**

## 7. Pinning information

### 7.1 Pinning



### 7.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
1A	1	data input
GND	2	ground (0 V)
2A	3	data input
2Y	4	data output
V <sub>CC</sub>	5	supply voltage
1Y	6	data output

## 8. Functional description

Table 4. Function table<sup>[1]</sup>

Input	Output
nA	nY
L	L
H	H

[1] H = HIGH voltage level; L = LOW voltage level.

## 9. Limiting values

**Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-	-50	mA
$V_I$	input voltage		[1] -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O < 0$ V	-	-50	mA
$V_O$	output voltage	Active mode	[1][2] -0.5	$V_{CC} + 0.5$	V
		Power-down mode	[1][2] -0.5	+6.5	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	$\pm 50$	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-	-100	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[3] -	300	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For SC-88 and SC-74 packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.

## 10. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	-	+125	°C

## 11. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b><math>T_{amb} = -40\text{ }^{\circ}\text{C to }+85\text{ }^{\circ}\text{C}</math> [1]</b>						
$V_{OL}$	LOW-level output voltage	$V_I = V_{T+}$ or $V_{T-}$				
		$I_O = 100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	-	-	0.1	V
		$I_O = 4\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.45	V
		$I_O = 8\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.3	V
		$I_O = 12\text{ mA}; V_{CC} = 2.7\text{ V}$	-	-	0.4	V
		$I_O = 24\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.55	V
		$I_O = 32\text{ mA}; V_{CC} = 4.5\text{ V}$	-	-	0.55	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{T+}$ or $V_{T-}$				
		$I_O = -100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -4\text{ mA}; V_{CC} = 1.65\text{ V}$	1.2	-	-	V
		$I_O = -8\text{ mA}; V_{CC} = 2.3\text{ V}$	1.9	-	-	V
		$I_O = -12\text{ mA}; V_{CC} = 2.7\text{ V}$	2.2	-	-	V
		$I_O = -24\text{ mA}; V_{CC} = 3.0\text{ V}$	2.3	-	-	V
		$I_O = -32\text{ mA}; V_{CC} = 4.5\text{ V}$	3.8	-	-	V
$I_I$	input leakage current	$V_I = 5.5\text{ V or GND}; V_{CC} = 5.5\text{ V}$	-	$\pm 0.1$	$\pm 5$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_I$ or $V_O = 5.5\text{ V}; V_{CC} = 0\text{ V}$	-	$\pm 0.1$	$\pm 10$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = V_{CC}$ or $\text{GND}; I_O = 0\text{ A}; V_{CC} = 5.5\text{ V}$	-	0.1	10	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6\text{ V}; I_O = 0\text{ A}; V_{CC} = 2.3\text{ V to }5.5\text{ V}$	-	5	500	$\mu\text{A}$
$C_I$	input capacitance		-	3.5	-	pF
<b><math>T_{amb} = -40\text{ }^{\circ}\text{C to }+125\text{ }^{\circ}\text{C}</math></b>						
$V_{OL}$	LOW-level output voltage	$V_I = V_{T+}$ or $V_{T-}$				
		$I_O = 100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	-	-	0.1	V
		$I_O = 4\text{ mA}; V_{CC} = 1.65\text{ V}$	-	-	0.70	V
		$I_O = 8\text{ mA}; V_{CC} = 2.3\text{ V}$	-	-	0.45	V
		$I_O = 12\text{ mA}; V_{CC} = 2.7\text{ V}$	-	-	0.60	V
		$I_O = 24\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.80	V
		$I_O = 32\text{ mA}; V_{CC} = 4.5\text{ V}$	-	-	0.80	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{T+}$ or $V_{T-}$				
		$I_O = -100\text{ }\mu\text{A}; V_{CC} = 1.65\text{ V to }5.5\text{ V}$	$V_{CC} - 0.1$	-	-	V
		$I_O = -4\text{ mA}; V_{CC} = 1.65\text{ V}$	0.95	-	-	V
		$I_O = -8\text{ mA}; V_{CC} = 2.3\text{ V}$	1.7	-	-	V
		$I_O = -12\text{ mA}; V_{CC} = 2.7\text{ V}$	1.9	-	-	V
		$I_O = -24\text{ mA}; V_{CC} = 3.0\text{ V}$	2.0	-	-	V
		$I_O = -32\text{ mA}; V_{CC} = 4.5\text{ V}$	3.4	-	-	V
$I_I$	input leakage current	$V_I = 5.5\text{ V or GND}; V_{CC} = 5.5\text{ V}$	-	$\pm 0.1$	$\pm 20$	$\mu\text{A}$

**Table 7. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{OFF}$	power-off leakage current	$V_I$ or $V_O = 5.5$ V; $V_{CC} = 0$ V	-	-	$\pm 20$	$\mu$ A
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V	-	-	40	$\mu$ A
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 0.6$ V; $I_O = 0$ A; $V_{CC} = 2.3$ V to 5.5 V	-	-	5	mA

[1] All typical values are measured at  $V_{CC} = 3.3$  V and  $T_{amb} = 25$  °C.

## 12. Dynamic characteristics

**Table 8. Dynamic characteristics**Voltages are referenced to GND (ground = 0 V); for test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$t_{pd}$	propagation delay	nA to nY; see <a href="#">Figure 5</a> <sup>[2]</sup>						
		$V_{CC} = 1.65$ V to 1.95 V	1.5	5.6	10.5	1.5	13.1	ns
		$V_{CC} = 2.3$ V to 2.7 V	1.0	3.7	6.5	1.0	8.5	ns
		$V_{CC} = 2.7$ V	1.0	3.8	6.5	1.0	8.5	ns
		$V_{CC} = 3.0$ V to 3.6 V	1.0	3.6	5.7	1.0	7.1	ns
		$V_{CC} = 4.5$ V to 5.5 V	1.0	2.7	4.3	1.0	5.4	ns
$C_{PD}$	power dissipation capacitance	per buffer; $V_{CC} = 3.3$ V; $V_I = GND$ to $V_{CC}$ <sup>[3]</sup>	-	16.3	-	-	-	pF

[1] Typical values are measured at  $T_{amb} = 25$  °C and  $V_{CC} = 1.8$  V, 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where: $f_i$  = input frequency in MHz; $f_o$  = output frequency in MHz; $C_L$  = output load capacitance in pF; $V_{CC}$  = supply voltage in V; $N$  = number of inputs switching; $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

13. Waveforms

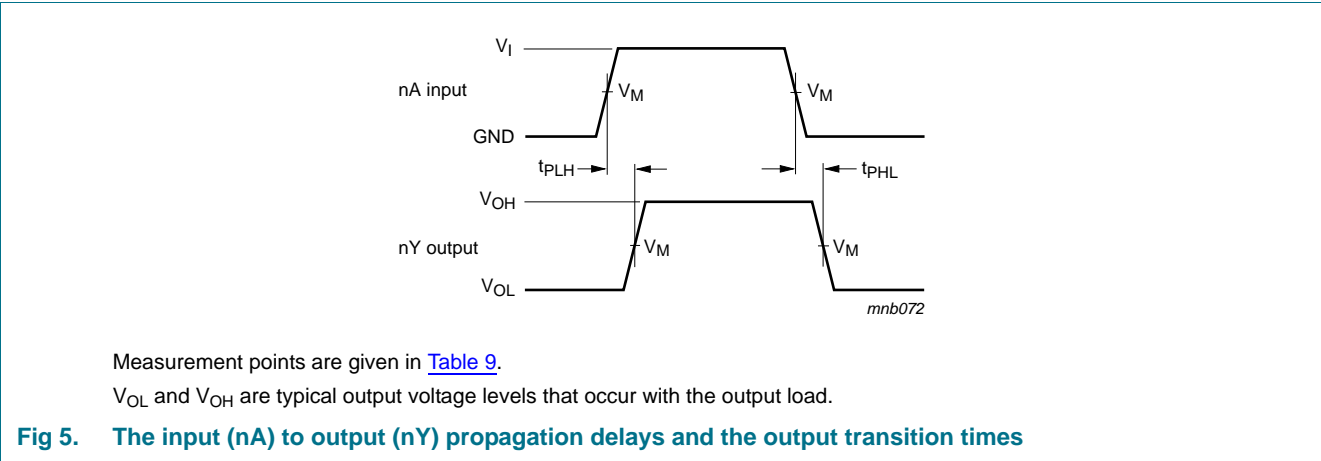


Table 9. Measurement points

Supply voltage	Input	Output
$V_{CC}$	$V_M$	$V_M$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$

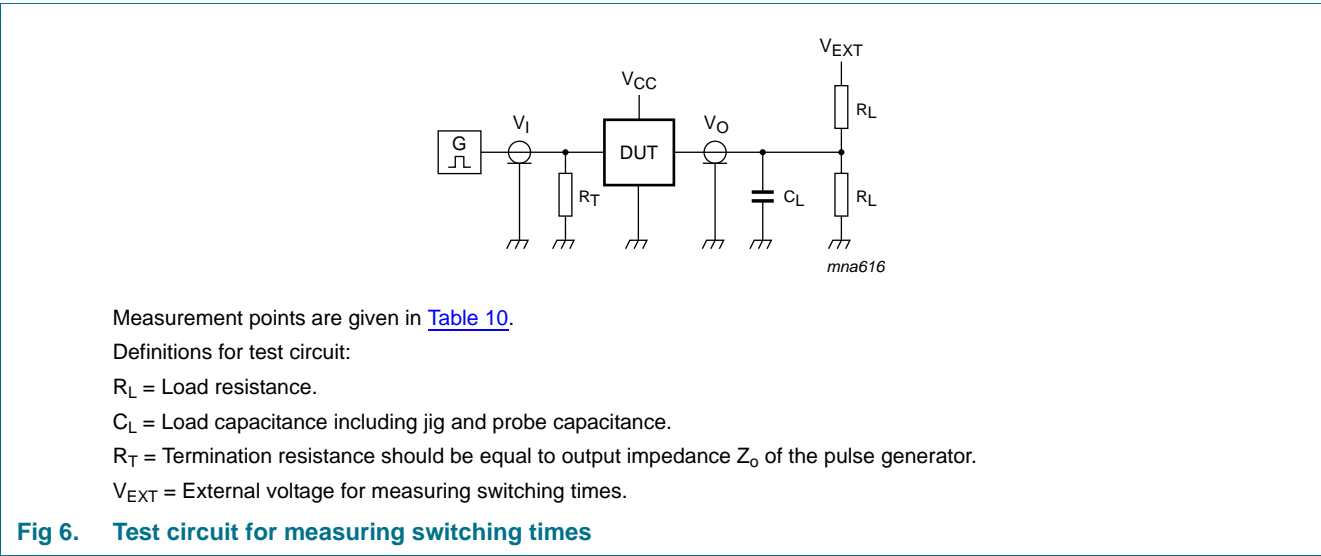


Table 10. Test data

Supply voltage	Input		Load		V <sub>EXT</sub>
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> , t <sub>f</sub>	C <sub>L</sub>	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>
1.65 V to 1.95 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V <sub>CC</sub>	≤ 2.5 ns	50 pF	500 Ω	open

## 14. Transfer characteristics

Table 11. Transfer characteristics

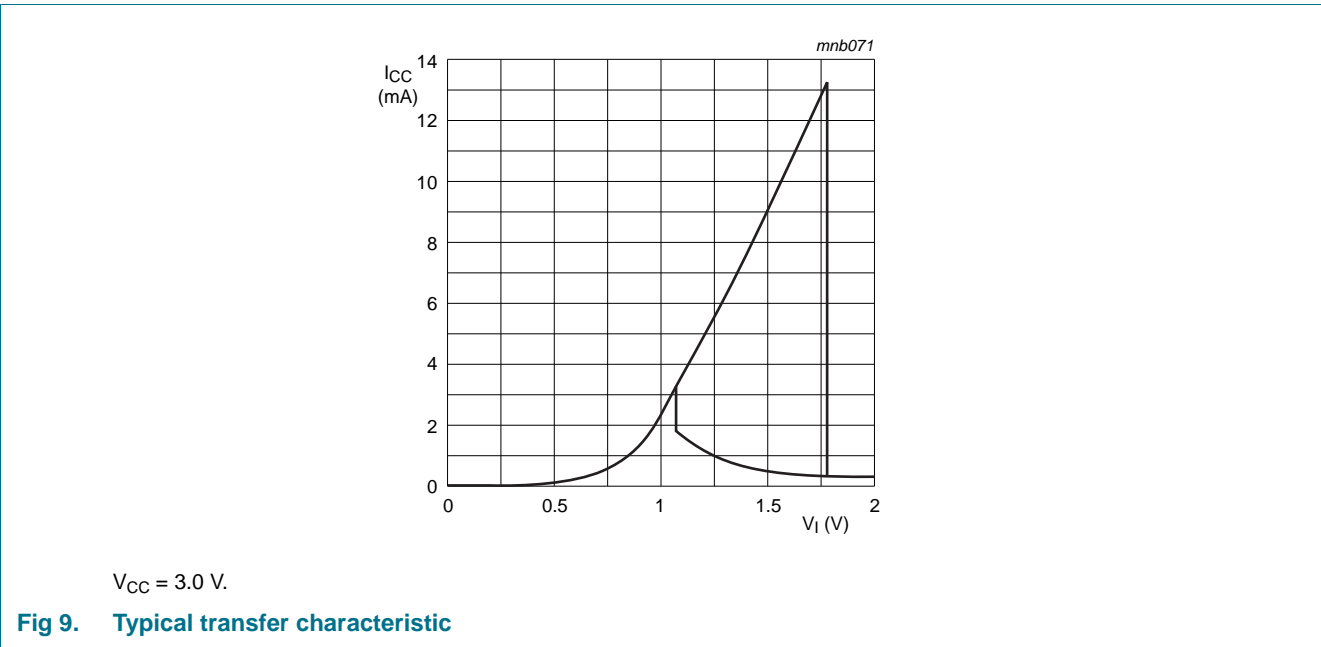
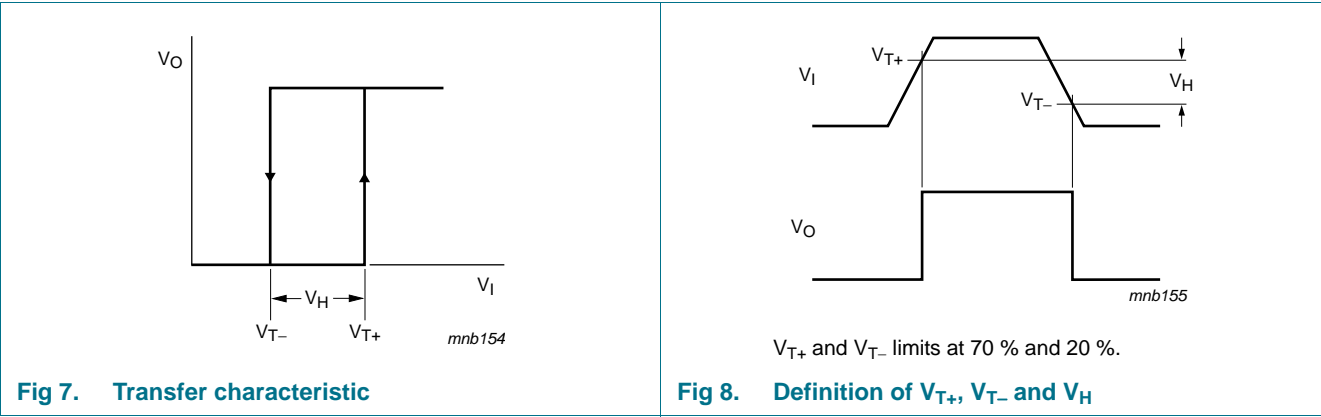
At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

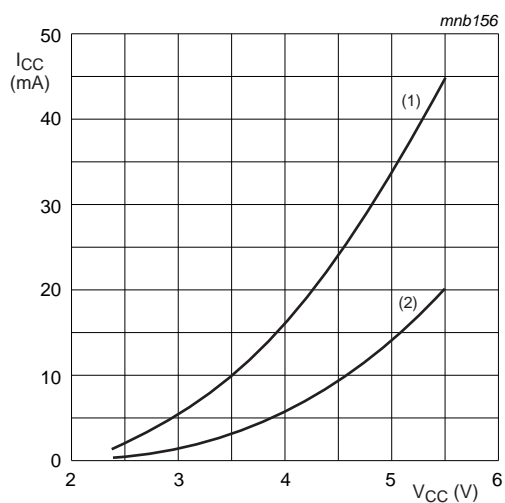
Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
V <sub>T+</sub>	positive-going threshold voltage	see <a href="#">Figure 7</a> and <a href="#">Figure 8</a>						
		V <sub>CC</sub> = 1.8 V	0.70	1.10	1.50	0.70	1.70	V
		V <sub>CC</sub> = 2.3 V	1.00	1.40	1.80	1.00	2.00	V
		V <sub>CC</sub> = 3.0 V	1.30	1.76	2.20	1.30	2.40	V
		V <sub>CC</sub> = 4.5 V	1.90	2.47	3.10	1.90	3.30	V
		V <sub>CC</sub> = 5.5 V	2.20	2.91	3.60	2.20	3.80	V
V <sub>T–</sub>	negative-going threshold voltage	see <a href="#">Figure 7</a> and <a href="#">Figure 8</a>						
		V <sub>CC</sub> = 1.8 V	0.25	0.61	0.90	0.25	1.10	V
		V <sub>CC</sub> = 2.3 V	0.40	0.80	1.15	0.40	1.35	V
		V <sub>CC</sub> = 3.0 V	0.60	1.04	1.50	0.60	1.70	V
		V <sub>CC</sub> = 4.5 V	1.00	1.55	2.00	1.00	2.20	V
		V <sub>CC</sub> = 5.5 V	1.20	1.86	2.30	1.20	2.50	V
V <sub>H</sub>	hysteresis voltage	(V <sub>T+</sub> – V <sub>T–</sub> ); see <a href="#">Figure 7</a> , <a href="#">Figure 8</a> and <a href="#">Figure 9</a>						
		V <sub>CC</sub> = 1.8 V	0.15	0.49	1.00	0.15	1.20	V
		V <sub>CC</sub> = 2.3 V	0.25	0.60	1.10	0.25	1.30	V
		V <sub>CC</sub> = 3.0 V	0.40	0.73	1.20	0.40	1.40	V
		V <sub>CC</sub> = 4.5 V	0.60	0.92	1.50	0.60	1.70	V
		V <sub>CC</sub> = 5.5 V	0.70	1.02	1.70	0.70	1.90	V

[1] All typical values are measured at T<sub>amb</sub> = 25 °C.



15. Waveforms transfer characteristics





(1) Positive-going edge

(2) Negative-going edge

Linear change of  $V_I$  between 0.8 V to 2.0 V. All values given are typical unless otherwise specified.

**Fig 10. Average  $I_{CC}$  as a function of  $V_{CC}$**

16. Package outline

Plastic surface-mounted package; 6 leadsSOT363

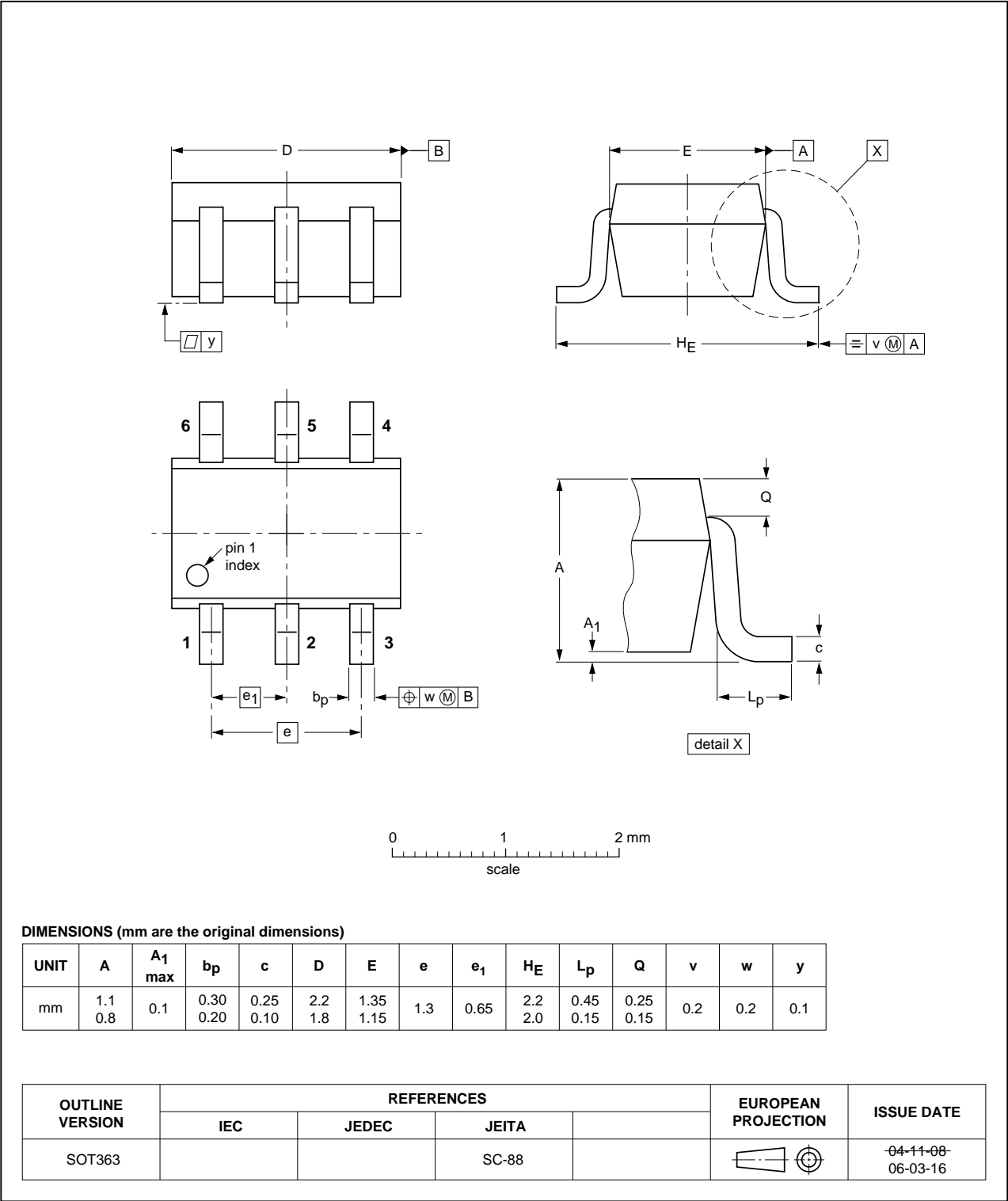


Fig 11. Package outline SOT363 (SC-88)

Plastic surface-mounted package (TSOP6); 6 leads

SOT457

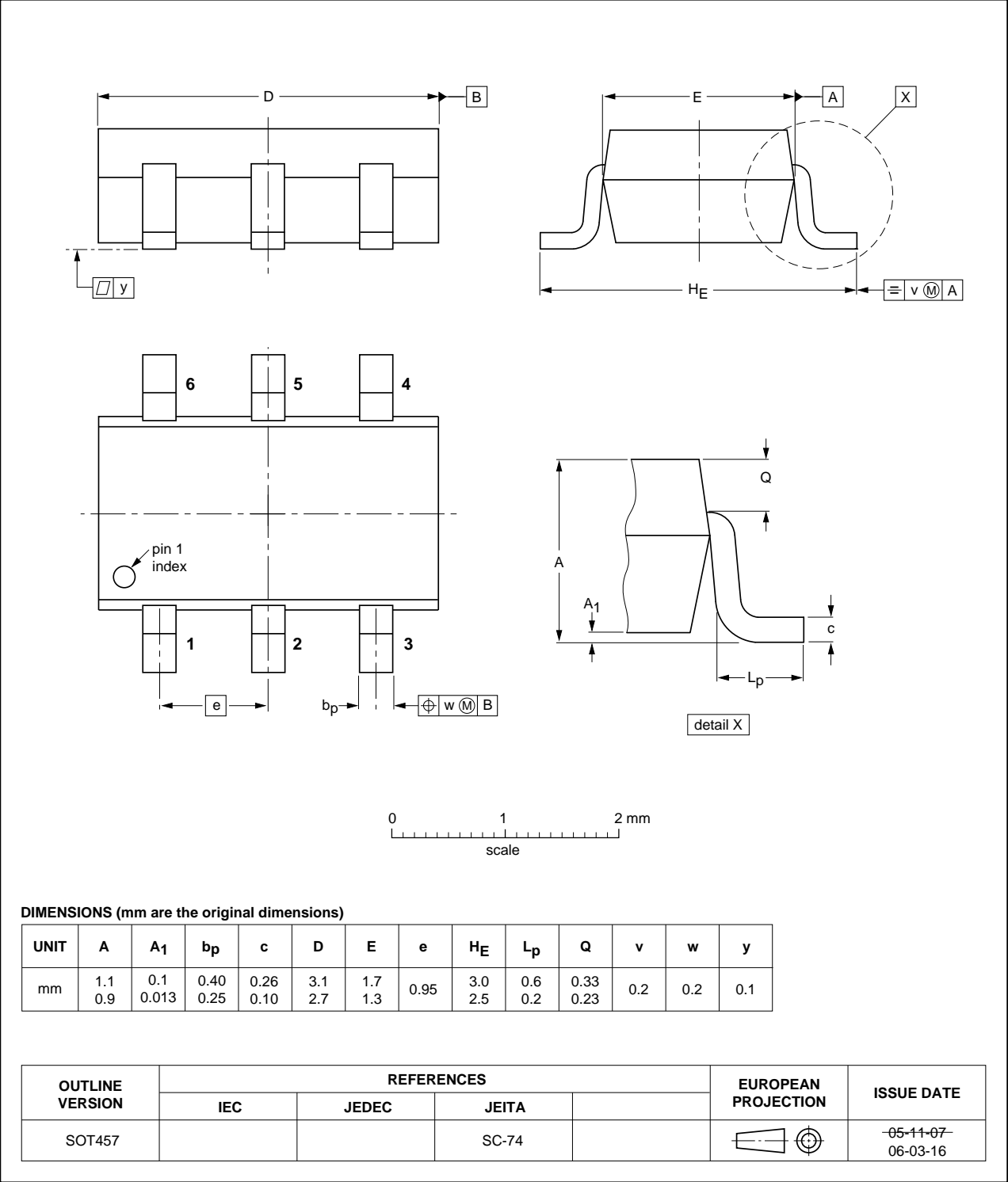


Fig 12. Package outline SOT457 (SC-74)

## 17. Abbreviations

Table 12. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic
MIL	Military

## 18. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC2G17_Q100 v.2	20130502	Product data sheet	-	74LVC2G17_Q100 v.1
Modifications:	• <a href="#">Table 3</a> : the description of pin 6 changed from data input to data output.			
74LVC2G17_Q100 v.1	20120807	Product data sheet	-	-

## 19. Legal information

### 19.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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**Limiting values** — Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

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